

高密度互連板（HDI）細線路用低粗糙度銅箔

Low profile copper foil for the Ultra fine line HDI



型號: MW-G / MLS-G / MLS-G2 / MLS-G3 /
HS2-VSP / SI-VSP / SI2-VSP / SI3-VSP

- 三井金屬銅箔薄且粗糙度低，適用於高密度互連板的微細線路設計，具有優越的蝕刻性/優良的抗撕強度/出色的耐熱特性。
- Mitsui Kinzoku thin and low roughness copper foils; Suitable for fine line HDI design with excellent etch-ability, bonding strength, and heat resistance properties.
- 具備穩定的量產能力，可充分供應客戶需求。
- Good track records of reliable and advanced production capability to fulfill customers' volume requirements.

Model No.	Cross Section Image	Roughness (Bonding side-Rz)	Thickness	Application (L/S)	Status
MW-G		4.0μm	12 μm	≥ 50/50μm	Mass Production
MLS-G		3.0um	12 um	40/40 ~ 50/50μm	
MLS-G2		2.0um	12 um	30/30 ~ 40/40μm	
MLS-G3		1.5um	12um	30/30 ~ 40/40μm	
HS2-VSP		1.0um	12 um	30/30 ~ 40/40μm	
SI-VSP		0.6um	12 um	30/30 ~ 40/40μm	Sampling
SI2-VSP		0.5um	12 um	30/30 ~ 40/40μm	

* 上表為代表性數據，非保證值。
* This is representative data not guarantee.